

PRE-RELEASE VERSION (FDIS)



**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 2-501: Test methods for materials for interconnection structures –
Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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TITLE: Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 2-501: Test methods for materials for interconnection structures – Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials

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NOTE FROM TC/SC OFFICERS:

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AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/XX/FDIS	91/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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Part 2-501: Test methods for materials for interconnection structures – Measurement of resilience strength and resilience strength retention factor of flexible dielectric materials

1 Scope

This part of IEC 61189 establishes a method suitable for testing the softness of FCCL (Flexible Copper Clad Laminate) products and related materials. This method determines the resilience under specified conditions. The test is performed on the sample as manufactured and without conditioning. The test does not apply to the resilience force lower than 10 mN.

2 Normative references

There are no normative references in this document.